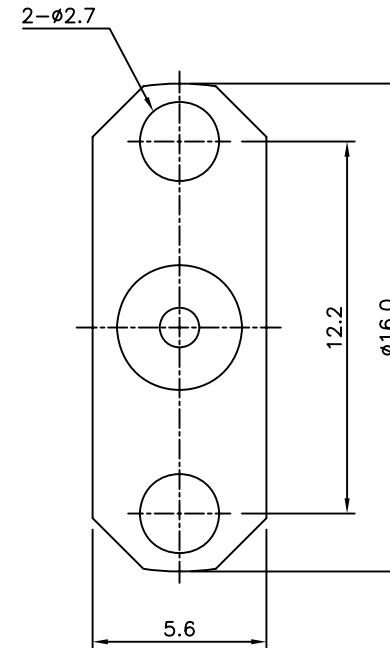
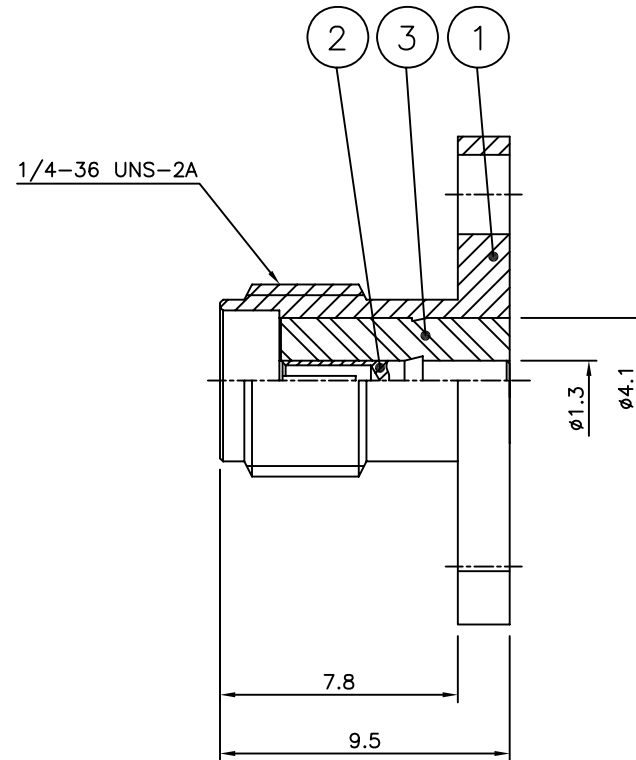
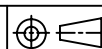


REVISION					
REV	DESCRIPTION	DRAWN	APPR	DATE	
1 R	Initial Registration	S.Y.EUN	I.C.KIM	2017.09.18.	
1	[설번처리No.201806-0006] 절연체 돌출 개선으로 인한 절연체 변경	S.Y.EUN	I.C.KIM	2018.06.18.	



1	3	INSULATOR	1	TEFLON		DIN02995-N/1 DIN01015-N/1
	2	CONTACT	1	BeCu C17300	Gold Plate	DCT00193-5/2
	1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00347-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2018. 06. 18.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM		
	±1°	CHECKED BY			
MATERIAL		DRAWN BY		TITLE	
-		S.Y.EUN		SMA50 SOLDER END JS-2H	
FINISH	-	SCALE	UNIT		A4
		4/1	mm		
				DWG NO. CN01108-7/5	
				REVISION 1 SHEET 1 of 1	